



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#10B-AUDI (2)

APPLICANT: Timothy R. SPOONER et al. GROUP: 2829
S. Benson
2/24/03

SERIAL NO: 10/006,966 EXAMINER: S. Geyer

FILED: December 5, 2001

FOR: A METHOD AND DEVICE FOR PROTECTING MICRO
ELECTROMECHANICAL SYSTEMS STRUCTURES
DURING DICING OF A WAFER

Assistant Commissioner of Patents
Washington, D.C. 20231

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TECHNOLOGY CENTER
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Sir:

AMENDMENT UNDER 37 C.F.R. 1.111

In response to the Office Action mailed December 4, 2002, the following amendments and remarks are respectfully submitted under 37 C.F.R. 1.111 in connection with the above-identified application.

In the Claims

Please amend the following claims:

35. (Amended) A method for protecting a MEMS structure during a dicing of a MEMS wafer to produce individual MEMS dies, comprising the steps of:

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(a) fabricating a MEMS wafer having a plurality of MEMS structure sites on a first side and a plurality of through holes on a second side;

(b) fabricating a wafer cap;